

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4858226

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DONG KIL SHIN	12/14/2015
CHUL KEUN YOON	12/29/2015
MIN KYU KANG	12/29/2015
GYU JEI LEE	12/29/2015
RECEIVING PARTY DATA	
Name:	SK HYNIX INC.
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB GYEONGGI-DO
City:	ICHEON
State/Country:	KOREA, REPUBLIC OF
Postal Code:	17336
Name:	INDUSTRY-ACADEMIC COOPERATION FOUNDATION, YEUNGNAM UNIVERSITY
Street Address:	280, DAEHAK-RO, GYEONGSANGBUK-DO
City:	GYEONGSAN
State/Country:	KOREA, REPUBLIC OF
Postal Code:	38541
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15913857
CORRESPONDENCE DATA	
Fax Number:	(425)348-3299
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	425-348-3500
Email:	docketing@ampacc.com
Correspondent Name:	AMPACC LAW GROUP, PLLC
Address Line 1:	6100 219TH ST. SW
Address Line 2:	SUITE 580
Address Line 4:	MOUNTLAKE TERRACE, WASHINGTON 98043
ATTORNEY DOCKET NUMBER:	100IM0629US1

NAME OF SUBMITTER:	STEVE Y. CHO
SIGNATURE:	/STEVE Y. CHO/
DATE SIGNED:	03/08/2018
Total Attachments: 4 source=4084178#page1.tif source=4084178#page2.tif source=4084178#page3.tif source=4084178#page4.tif	

DECLARATION AND ASSIGNMENT OF PATENT APPLICATION

As a below named inventor, I hereby declare that:

This declaration is directed to the application attached hereto, or if not attached hereto, the below-identified application:

Title of Invention: METHOD OF MEASURING AN ADHESIVE
 FORCE OF INTERLAYER ADHESIVE LAYER
 IN TENSILE MODE FOR STACKED
 SEMICONDUCTOR DEVICE AND APPARATUS
 FOR MEASURING THE SAME

Filing Date: March 6, 2018

Application No.: 15/913,857

Attorney Docket No.: 100IM0629US1

The application was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statements made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, the below named individual(s), hereinafter referred to as "Assignors," are the inventor(s) of the invention described and set forth in the above-identified application for United States Letters Patent;

WHEREAS, SK hynix Inc., located at 2091, Gyeongchung-daero, Bubal-eub, Icheon-si, Gyeonggi-do 17336, Republic of Korea, and Industry-Academic Cooperation Foundation, Yeungnam University, located at 280, Daehak-ro, Gyeongsan-si, Gyeongsangbuk-do 38541, Republic of Korea, hereinafter referred to as "ASSIGNEE," is desirous of acquiring ASSIGNORS' interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all their right, title and interest in and to the said invention and application including any corresponding foreign application, and in and to any Letters Patent which may hereafter be granted on the same in the United States and any corresponding foreign application, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignors had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such

other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request AMPACC Law Group, PLLC, 6100 219th Street SW, Suite 580, Mountlake Terrace, WA 98043, to insert herein above the title, application number, and filing date of said application when known.

IN TESTIMONY WHEREOF, each below named inventor, collectively Assignors, has signed on the dates indicated.

Dec. 14, 2015
Date:

Dong Kil Shin
Inventor's Name: Dong Kil SHIN

Date:

Inventor's Name: Chul Keun YOON

Date:

Inventor's Name: Min Kyu KANG

Date:

Inventor's Name: Gyu Jei LEE

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other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns.

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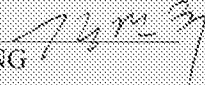
Date:

Inventor's Name: Dong Kil SHIN

Date: 6/29/2015

Inventor's Name: Chul Keun YOON 

Date: 12/29/2015

Inventor's Name: Min Kyu KANG 

Date: 12/29/2015

Inventor's Name: Gyu Jei LEE 